



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **FUKASAWA, et al.**

Serial No.: **09/029,608**

Filed: **May 15, 1998**

Group Art Unit: **2827**

Examiner: **D. Graybill**

P.T.O. Confirmation No.: **6285**

For. **METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE, SEMICONDUCTOR**

**AMENDMENT UNDER 37 CFR §1.111**

Commissioner for Patents  
Washington, D.C. 20231

October 25, 2002

Sir:

In response to the Office Action dated **July 25, 2002**, please amend the above identified application as follows:

**IN THE CLAIMS:**

Please cancel claims ~~87-90~~, ~~117~~, ~~118~~, ~~121~~, ~~122~~, ~~124-126~~ and ~~128~~, without prejudice or disclaimer.

Please amend claims 109-112, 115, 119, 123 and 127 as follows:

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109. (Twice Amended) A semiconductor device comprising:  
a semiconductor element having a surface on which protruding electrodes are formed;  
a resin layer formed on the surface of the semiconductor element so as to seal the protruding  
electrodes except end portions thereof; and  
external connection protruding electrodes provided to the end portions of the protruding  
electrodes that protrude from the resin layer,

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